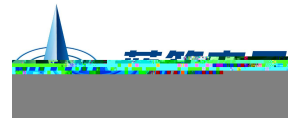


/ Revised record

F	2017-9				
G	2022-1-27	6	0 n , 0		

TL432

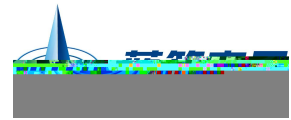
□ . G □ JaJ



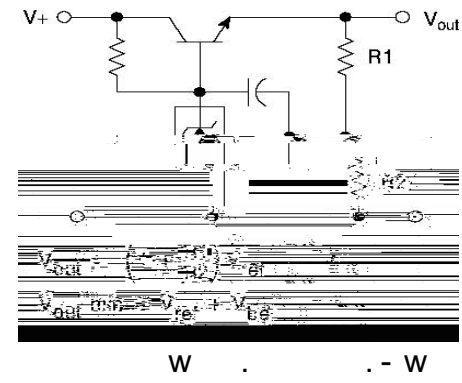
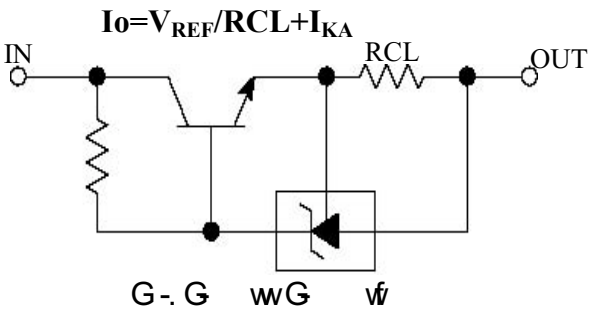
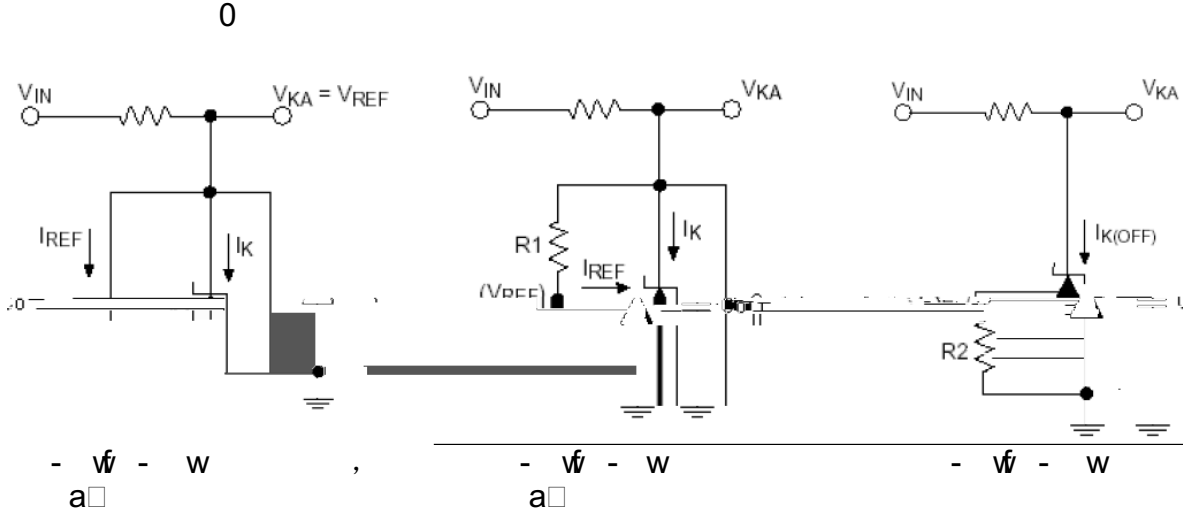
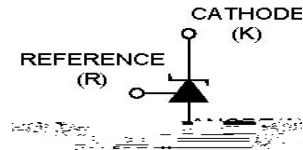
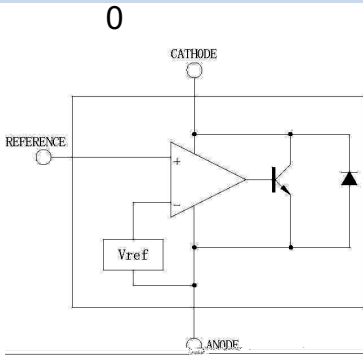
DATASHEET

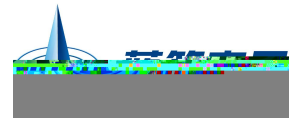
. w - w

. - G



& Test circuits & Typical Application





/ Electrical Characteristic Curve

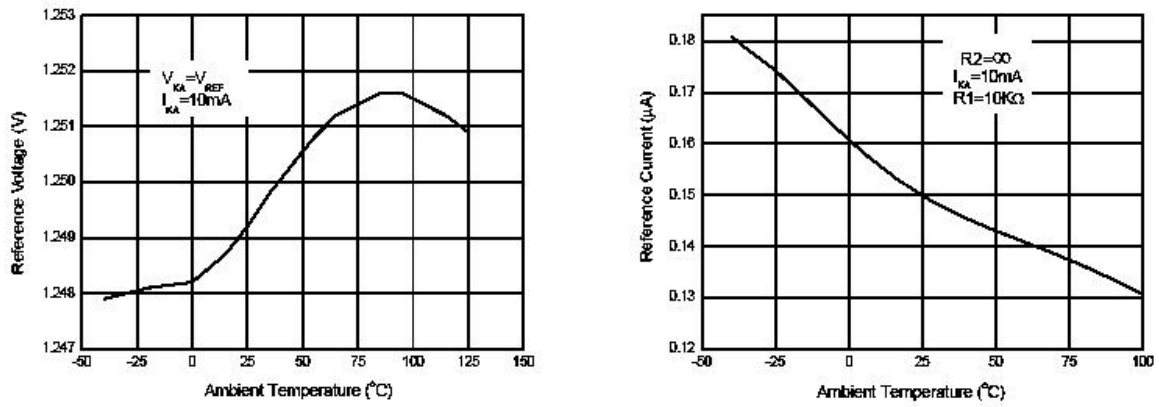
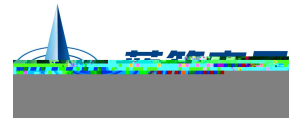
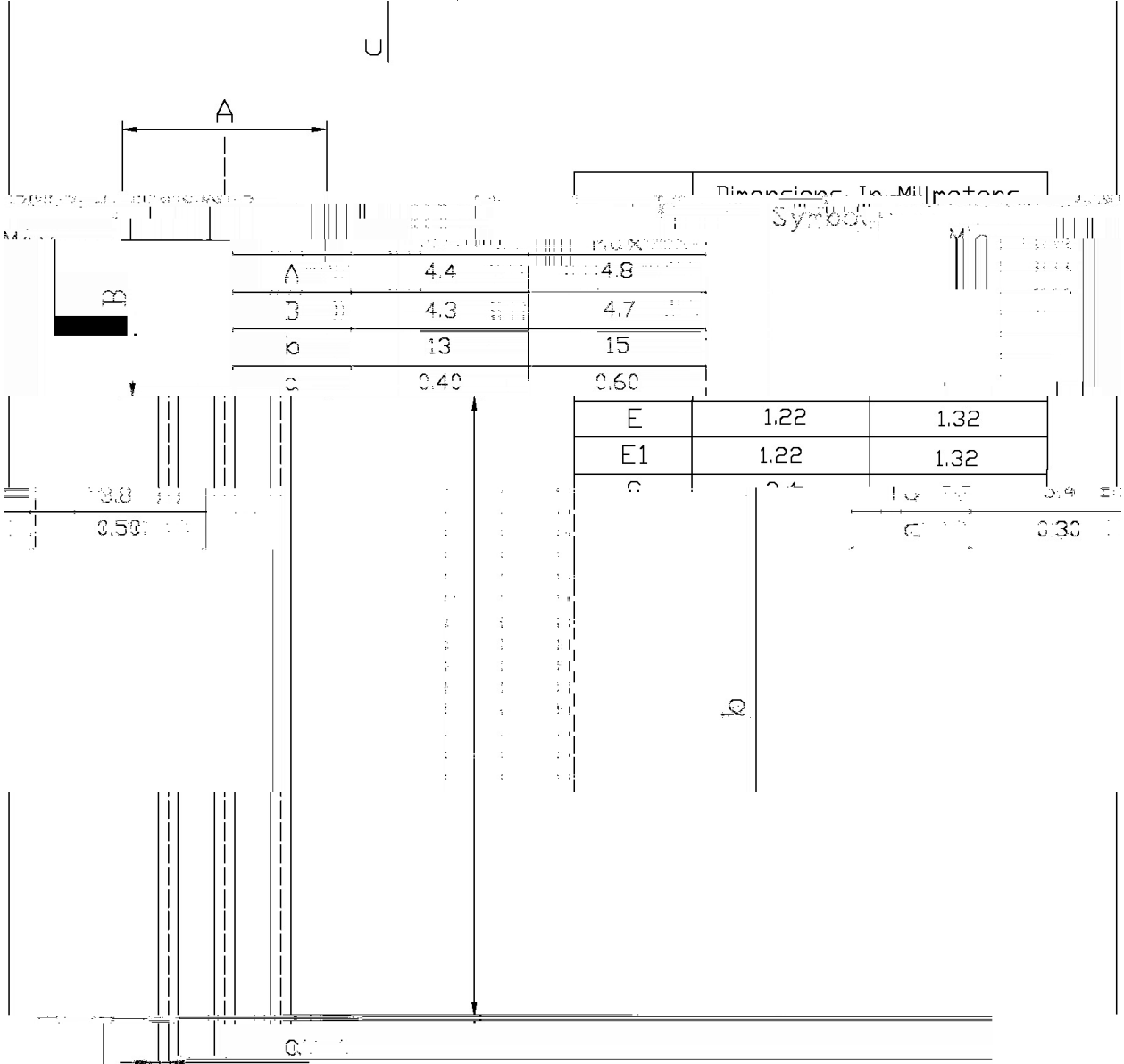
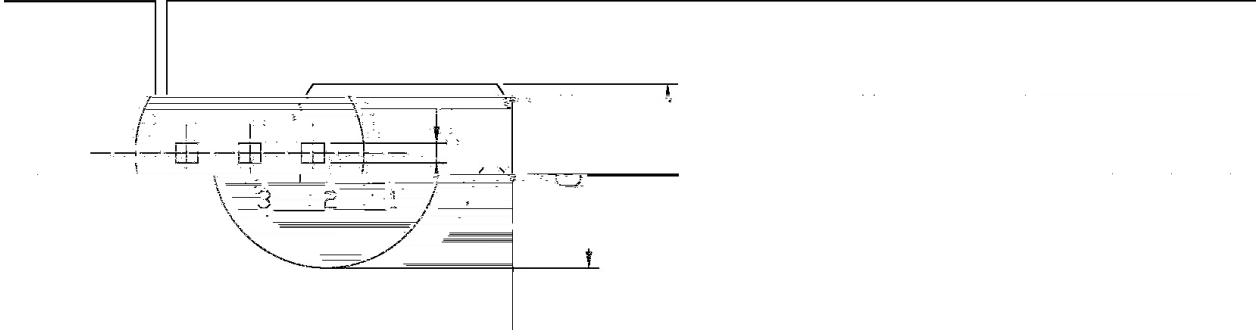


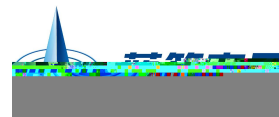
Figure 7. Reference Voltage vs. Ambient Temperature



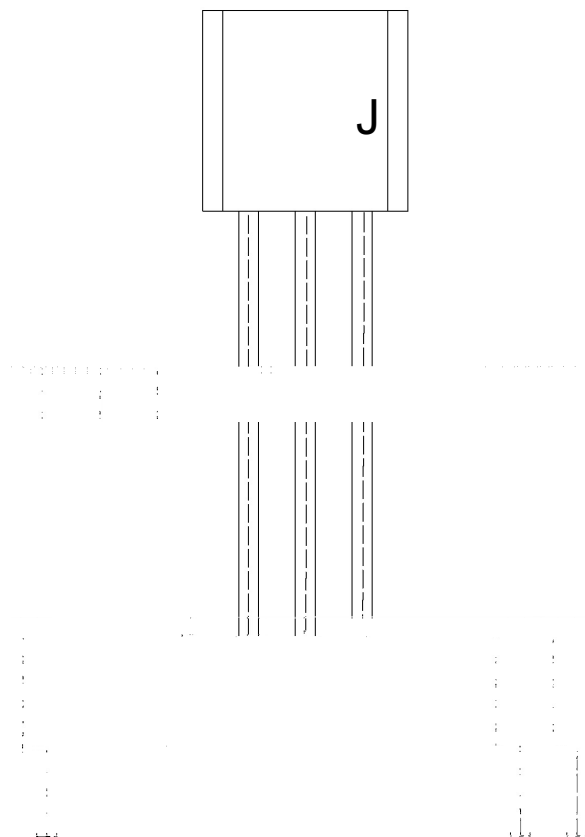


/ Package Dimensions





/ Marking Instructions



说明：

□ : 为公司代码

J : 为产品型号

0 为 分档代码

**** : 为生产批号代码，随生产批号变化。

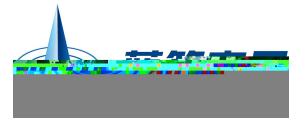
- 0

0 2. G □

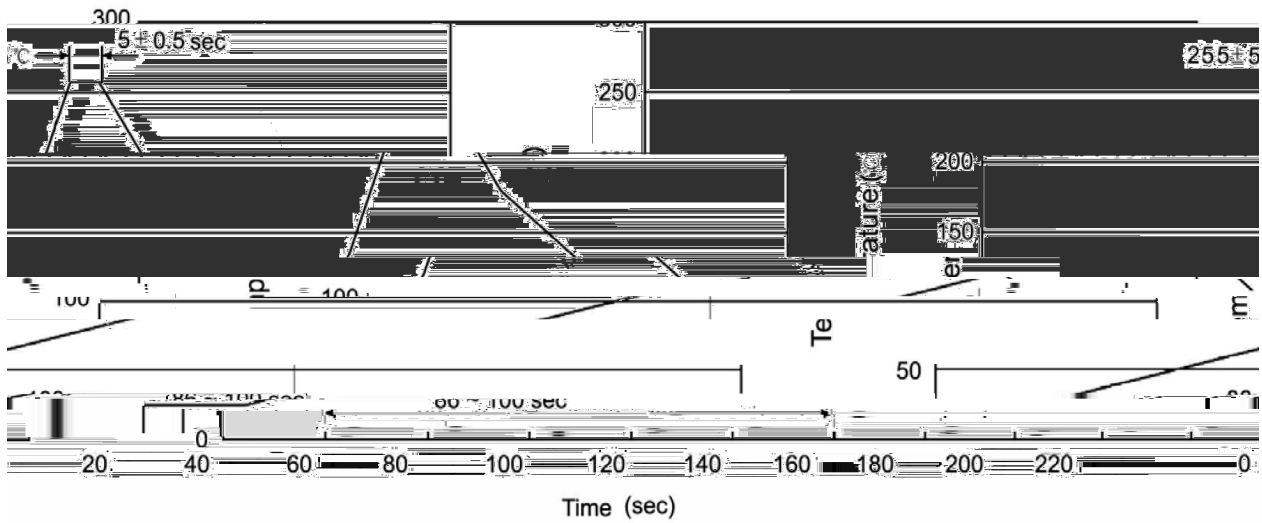
J0 w f- 2 □

0 . f.- G

0 - □ f fn.G t -n - □



() / Temperature Profile for Dip Soldering(Pb-Free)



- 0

J a a a f □ wn .-G □ a°C 0a a f □

J J ± ±a □ f J □ . 2 □ ± °C w- G ±a □ f □

J a°C h f □ □ G 2 □ a°C h f □

/ Resistance to Soldering Heat Test Conditions

J a ± °C a ± f □ 2 □ a °C 0a f

/ Packaging SPEC.

h

. f . 2 封装形式	G- 包装数量				G G 包装尺寸		G-:
					袋	盒	箱

h

. f . 2 封装形式	G- 包装数量				G G 包装尺寸		G-:
					盒	箱	
						小箱 大箱	

/ Notices